

ABSTRACT

A package substrate includes a base insulating layer, a first main line pattern on a first surface of the base insulating layer, a plurality of first conductive pads on the first surface of the base insulating layer, a plurality of first branch line patterns on the first surface of the base insulating layer, the plurality of first branch line patterns extending between the first main line pattern and the plurality of first conductive pads; and a first insulating layer on the first surface of the base insulating layer, the first insulating layer including a plurality of first through grooves. Each of the plurality of first branch line patterns includes a first cut portion, a first segment and a second segment separated from each other by the first cut portion, and the plurality of first through grooves overlap first cut portions.

FIG. 3